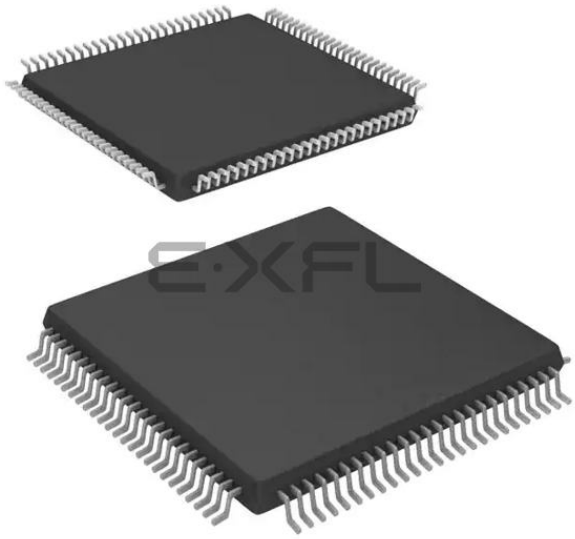

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	1536
Total RAM Bits	18432
Number of I/O	71
Number of Gates	60000
Voltage - Supply	1.14V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	100-TQFP
Supplier Device Package	100-VQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/agl060v2-vq100

1 – IGLOO Device Family Overview

General Description

The IGLOO family of flash FPGAs, based on a 130-nm flash process, offers the lowest power FPGA, a single-chip solution, small footprint packages, reprogrammability, and an abundance of advanced features.

The Flash*Freeze technology used in IGLOO devices enables entering and exiting an ultra-low power mode that consumes as little as 5 µW while retaining SRAM and register data. Flash*Freeze technology simplifies power management through I/O and clock management with rapid recovery to operation mode.

The Low Power Active capability (static idle) allows for ultra-low power consumption (from 12 µW) while the IGLOO device is completely functional in the system. This allows the IGLOO device to control system power management based on external inputs (e.g., scanning for keyboard stimulus) while consuming minimal power.

Nonvolatile flash technology gives IGLOO devices the advantage of being a secure, low power, single-chip solution that is Instant On. IGLOO is reprogrammable and offers time-to-market benefits at an ASIC-level unit cost.

These features enable designers to create high-density systems using existing ASIC or FPGA design flows and tools.

IGLOO devices offer 1 kbit of on-chip, reprogrammable, nonvolatile FlashROM storage as well as clock conditioning circuitry based on an integrated phase-locked loop (PLL). The AGL015 and AGL030 devices have no PLL or RAM support. IGLOO devices have up to 1 million system gates, supported with up to 144 kbits of true dual-port SRAM and up to 300 user I/Os.

M1 IGLOO devices support the high-performance, 32-bit Cortex-M1 processor developed by ARM for implementation in FPGAs. Cortex-M1 is a soft processor that is fully implemented in the FPGA fabric. It has a three-stage pipeline that offers a good balance between low power consumption and speed when implemented in an M1 IGLOO device. The processor runs the ARMv6-M instruction set, has a configurable nested interrupt controller, and can be implemented with or without the debug block. Cortex-M1 is available for free from Microsemi for use in M1 IGLOO FPGAs.

The ARM-enabled devices have ordering numbers that begin with M1AGL and do not support AES decryption.

Flash*Freeze Technology

The IGLOO device offers unique Flash*Freeze technology, allowing the device to enter and exit ultra-low power Flash*Freeze mode. IGLOO devices do not need additional components to turn off I/Os or clocks while retaining the design information, SRAM content, and registers. Flash*Freeze technology is combined with in-system programmability, which enables users to quickly and easily upgrade and update their designs in the final stages of manufacturing or in the field. The ability of IGLOO V2 devices to support a wide range of core voltage (1.2 V to 1.5 V) allows further reduction in power consumption, thus achieving the lowest total system power.

When the IGLOO device enters Flash*Freeze mode, the device automatically shuts off the clocks and inputs to the FPGA core; when the device exits Flash*Freeze mode, all activity resumes and data is retained.

The availability of low power modes, combined with reprogrammability, a single-chip and single-voltage solution, and availability of small-footprint, high pin-count packages, make IGLOO devices the best fit for portable electronics.

Table 2-20 • **Different Components Contributing to the Static Power Consumption in IGLOO Devices For IGLOO V2 or V5 Devices, 1.5 V DC Core Supply Voltage**

Parameter	Definition	Device-Specific Static Power (mW)							
		AGL1000	**AGL600**	**AGL400**	**AGL250**	**AGL125**	**AGL060**	**AGL030**	**AGL015**
PDC1	Array static power in Active mode	See Table 2-12 on page 2-9.							
PDC2	Array static power in Static (Idle) mode	See Table 2-11 on page 2-8.							
PDC3	Array static power in Flash*Freeze mode	See Table 2-9 on page 2-7.							
PDC4	Static PLL contribution	1.84							
PDC5	Bank quiescent power (V_{CCI}-dependent)	See Table 2-12 on page 2-9.							
PDC6	I/O input pin static power (standard-dependent)	See Table 2-13 on page 2-10 through Table 2-15 on page 2-11.							
PDC7	I/O output pin static power (standard-dependent)	See Table 2-16 on page 2-11 through Table 2-18 on page 2-12.							

*Note: *For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or SmartPower tool in Libero SoC.*

Guidelines

Toggle Rate Definition

A toggle rate defines the frequency of a net or logic element relative to a clock. It is a percentage. If the toggle rate of a net is 100%, this means that this net switches at half the clock frequency. Below are some examples:

- The average toggle rate of a shift register is 100% because all flip-flop outputs toggle at half of the clock frequency.
- The average toggle rate of an 8-bit counter is 25%:
  - Bit 0 (LSB) = 100%
  - Bit 1 = 50%
  - Bit 2 = 25%
  - …
  - Bit 7 (MSB) = 0.78125%
  - Average toggle rate = (100% + 50% + 25% + 12.5% + . . . + 0.78125%) / 8

Enable Rate Definition

Output enable rate is the average percentage of time during which tristate outputs are enabled. When nontristate output buffers are used, the enable rate should be 100%.

Table 2-23 • **Toggle Rate Guidelines Recommended for Power Calculation**

Component	Definition	Guideline
α_1	Toggle rate of VersaTile outputs	10%
α_2	I/O buffer toggle rate	10%

Table 2-24 • **Enable Rate Guidelines Recommended for Power Calculation**

Component	Definition	Guideline
β_1	I/O output buffer enable rate	100%
β_2	RAM enable rate for read operations	12.5%
β_3	RAM enable rate for write operations	12.5%

2.5 V LVCMOS

Low-Voltage CMOS for 2.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 2.5 V applications.

Table 2-79 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks

2.5 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSH	IOSL	IIL[1]	IIH[2]
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA[3]	Max. mA[3]	µA[4]	µA[4]
2 mA	–0.3	0.7	1.7	2.7	0.7	1.7	2	2	16	18	10	10
4 mA	–0.3	0.7	1.7	2.7	0.7	1.7	4	4	16	18	10	10
6 mA	–0.3	0.7	1.7	2.7	0.7	1.7	6	6	32	37	10	10
8 mA	–0.3	0.7	1.7	2.7	0.7	1.7	8	8	32	37	10	10
12 mA	–0.3	0.7	1.7	2.7	0.7	1.7	12	12	65	74	10	10
16 mA	–0.3	0.7	1.7	2.7	0.7	1.7	16	16	83	87	10	10
24 mA	–0.3	0.7	1.7	2.7	0.7	1.7	24	24	169	124	10	10

Notes:

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

Table 2-80 • Minimum and Maximum DC Input and Output Levels Applicable to Standard Plus I/O Banks

2.5 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSH	IOSL	IIL[1]	IIH[2]
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA[3]	Max. mA[3]	µA[4]	µA[4]
2 mA	–0.3	0.7	1.7	2.7	0.7	1.7	2	2	16	18	10	10
4 mA	–0.3	0.7	1.7	2.7	0.7	1.7	4	4	16	18	10	10
6 mA	–0.3	0.7	1.7	2.7	0.7	1.7	6	6	32	37	10	10
8 mA	–0.3	0.7	1.7	2.7	0.7	1.7	8	8	32	37	10	10
12 mA	–0.3	0.7	1.7	2.7	0.7	1.7	12	12	65	74	10	10

Notes:

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

Applies to 1.2 V Core Voltage

Table 2-89 • **2.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	1.55	5.59	0.26	1.20	1.10	5.68	5.14	2.82	2.80	11.47	10.93	ns
4 mA	Std.	1.55	5.59	0.26	1.20	1.10	5.68	5.14	2.82	2.80	11.47	10.93	ns
6 mA	Std.	1.55	4.76	0.26	1.20	1.10	4.84	4.47	3.10	3.33	10.62	10.26	ns
8 mA	Std.	1.55	4.76	0.26	1.20	1.10	4.84	4.47	3.10	3.33	10.62	10.26	ns
12 mA	Std.	1.55	4.17	0.26	1.20	1.10	4.23	3.99	3.30	3.67	10.02	9.77	ns
16 mA	Std.	1.55	3.98	0.26	1.20	1.10	4.04	3.88	3.34	3.76	9.83	9.66	ns
24 mA	Std.	1.55	3.90	0.26	1.20	1.10	3.96	3.90	3.40	4.09	9.75	9.68	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-90 • **2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	1.55	3.33	0.26	1.20	1.10	3.38	3.09	2.82	2.91	9.17	8.88	ns
4 mA	Std.	1.55	3.33	0.26	1.20	1.10	3.38	3.09	2.82	2.91	9.17	8.88	ns
6 mA	Std.	1.55	2.89	0.26	1.20	1.10	2.93	2.56	3.10	3.45	8.72	8.34	ns
8 mA	Std.	1.55	2.89	0.26	1.20	1.10	2.93	2.56	3.10	3.45	8.72	8.34	ns
12 mA	Std.	1.55	2.64	0.26	1.20	1.10	2.67	2.29	3.30	3.79	8.46	8.08	ns
16 mA	Std.	1.55	2.59	0.26	1.20	1.10	2.63	2.24	3.34	3.88	8.41	8.03	ns
24 mA	Std.	1.55	2.60	0.26	1.20	1.10	2.64	2.18	3.40	4.22	8.42	7.97	ns

Notes:

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

Table 2-91 • **2.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V
Applicable to Standard Plus Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	1.55	5.02	0.26	1.19	1.10	5.11	4.60	2.50	2.62	10.89	10.38	ns
4 mA	Std.	1.55	5.02	0.26	1.19	1.10	5.11	4.60	2.50	2.62	10.89	10.38	ns
6 mA	Std.	1.55	4.21	0.26	1.19	1.10	4.27	4.00	2.76	3.10	10.06	9.79	ns
8 mA	Std.	1.55	4.21	0.26	1.19	1.10	4.27	4.00	2.76	3.10	10.06	9.79	ns
12 mA	Std.	1.55	3.66	0.26	1.19	1.10	3.71	3.55	2.94	3.41	9.50	9.34	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-107 • **1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V
Applicable to Standard Plus Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	1.55	6.32	0.26	1.11	1.10	6.43	5.81	2.47	2.16	12.22	11.60	ns
4 mA	Std.	1.55	5.27	0.26	1.11	1.10	5.35	5.01	2.78	2.92	11.14	10.79	ns
6 mA	Std.	1.55	4.56	0.26	1.11	1.10	4.64	4.44	3.00	3.30	10.42	10.22	ns
8 mA	Std.	1.55	4.56	0.26	1.11	1.10	4.64	4.44	3.00	3.30	10.42	10.22	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-108 • **1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V
Applicable to Standard Plus Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	1.55	3.22	0.26	1.11	1.10	3.26	3.18	2.47	2.20	9.05	8.97	ns
4 mA	Std.	1.55	2.72	0.26	1.11	1.10	2.75	2.50	2.78	3.01	8.54	8.29	ns
6 mA	Std.	1.55	2.43	0.26	1.11	1.10	2.47	2.16	2.99	3.39	8.25	7.94	ns
8 mA	Std.	1.55	2.43	0.26	1.11	1.10	2.47	2.16	2.99	3.39	8.25	7.94	ns

Notes:

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

Table 2-109 • **1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V
Applicable to Standard Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
2 mA	Std.	1.55	6.13	0.26	1.08	1.10	6.24	5.79	2.08	1.78	ns
4 mA	Std.	1.55	5.17	0.26	1.08	1.10	5.26	4.98	2.38	2.54	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-110 • **1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V
Applicable to Standard Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
2 mA	Std.	3.06	0.26	1.08	1.10	3.10	3.01	2.08	1.83	3.06	ns
4 mA	Std.	2.60	0.26	1.08	1.10	2.64	2.33	2.38	2.62	2.60	ns

Notes:

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

I/O Register Specifications

Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Preset

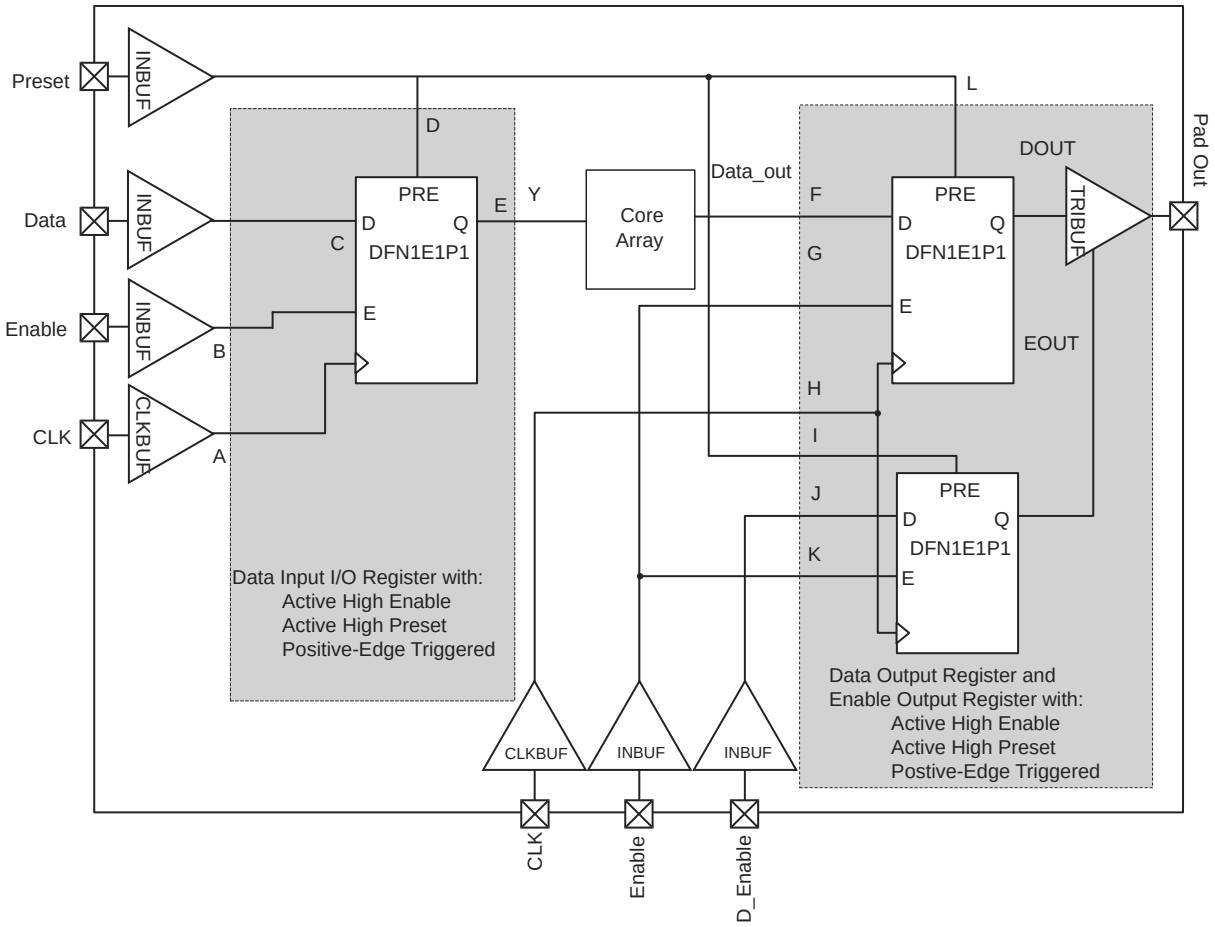


Figure 2-16 • **Timing Model of Registered I/O Buffers with Synchronous Enable and Asynchronous Preset**

DDR Module Specifications

Input DDR Module

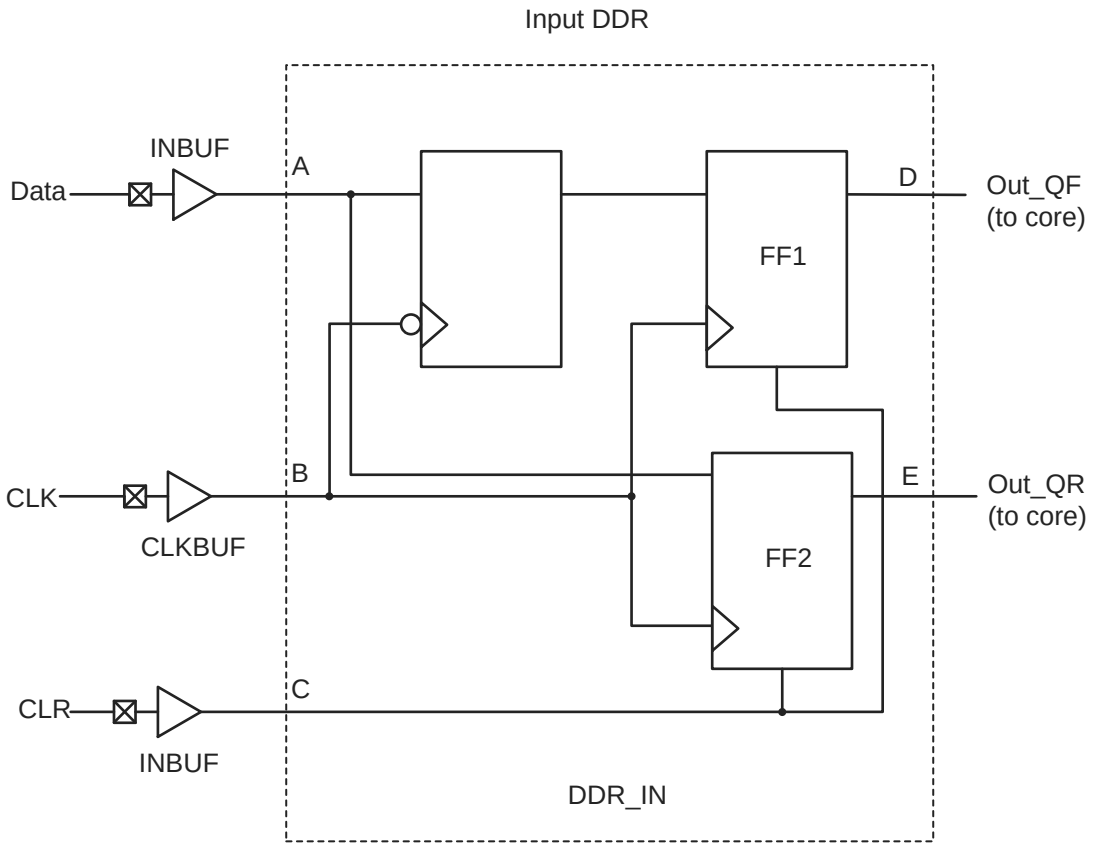
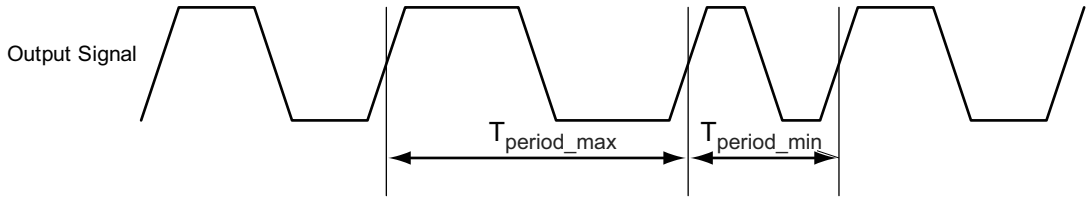


Figure 2-21 • **Input DDR Timing Model**

Table 2-163 • **Parameter Definitions**

Parameter Name	Parameter Definition	Measuring Nodes (from, to)
$t_{DDRICLKQ1}$	Clock-to-Out Out_QR	B, D
$t_{DDRICLKQ2}$	Clock-to-Out Out_QF	B, E
$t_{DDRISUD}$	Data Setup Time of DDR input	A, B
t_{DDRIHD}	Data Hold Time of DDR input	A, B
$t_{DDRICLR2Q1}$	Clear-to-Out Out_QR	C, D
$t_{DDRICLR2Q2}$	Clear-to-Out Out_QF	C, E
$t_{DDRIREMCLR}$	Clear Removal	C, B
$t_{DDRIRECCLR}$	Clear Recovery	C, B



Note: Peak-to-peak jitter measurements are defined by $T_{peak\text{-}to\text{-}peak} = T_{period\_max} – T_{period\_min}$.

Figure 2-30 • **Peak-to-Peak Jitter Definition**

Timing Characteristics

1.5 V DC Core Voltage

Table 2-191 • RAM4K9
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t_{AS}	Address setup time	0.83	ns
t_{AH}	Address hold time	0.16	ns
t_{ENS}	REN, WEN setup time	0.81	ns
t_{ENH}	REN, WEN hold time	0.16	ns
t_{BKS}	BLK setup time	1.65	ns
t_{BKH}	BLK hold time	0.16	ns
t_{DS}	Input data (DIN) setup time	0.71	ns
t_{DH}	Input data (DIN) hold time	0.36	ns
t_{CKQ1}	Clock High to new data valid on DOUT (output retained, WMODE = 0)	3.53	ns
	Clock High to new data valid on DOUT (flow-through, WMODE = 1)	3.06	ns
t_{CKQ2}	Clock High to new data valid on DOUT (pipelined)	1.81	ns
t_{C2CWWL}[1]	Address collision clk-to-clk delay for reliable write after write on same address – Applicable to Closing Edge	0.23	ns
t_{C2CRWL}[1]	Address collision clk-to-clk delay for reliable read access after write on same address – Applicable to Opening Edge	0.35	ns
t_{C2CWRH}[1]	Address collision clk-to-clk delay for reliable write access after read on same address – Applicable to Opening Edge	0.41	ns
t_{RSTBQ}	RESET Low to data out Low on DOUT (flow-through)	2.06	ns
	RESET Low to data out Low on DOUT (pipelined)	2.06	ns
$t_{REMRSTB}$	RESET removal	0.61	ns
$t_{RECRSTB}$	RESET recovery	3.21	ns
$t_{MPWRSTB}$	RESET minimum pulse width	0.68	ns
t_{CYC}	Clock cycle time	6.24	ns
F_{MAX}	Maximum frequency	160	MHz

Notes:

1. *For more information, refer to the application note* Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs.
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

1.2 V DC Core Voltage

***Table 2-196* • FIFO**
Worst Commercial-Case Conditions: T_J = 70°C, VCC = 1.14 V

Parameter	Description	Std.	Units
t_{ENS}	REN, WEN Setup Time	4.13	ns
t_{ENH}	REN, WEN Hold Time	0.31	ns
t_{BKS}	BLK Setup Time	0.47	ns
t_{BKH}	BLK Hold Time	0.00	ns
t_{DS}	Input Data (WD) Setup Time	1.56	ns
t_{DH}	Input Data (WD) Hold Time	0.49	ns
t_{CKQ1}	Clock High to New Data Valid on RD (flow-through)	6.80	ns
t_{CKQ2}	Clock High to New Data Valid on RD (pipelined)	3.62	ns
t_{RCKEF}	RCLK High to Empty Flag Valid	7.23	ns
t_{WCKFF}	WCLK High to Full Flag Valid	6.85	ns
t_{CKAF}	Clock High to Almost Empty/Full Flag Valid	26.61	ns
t_{RSTFG}	RESET Low to Empty/Full Flag Valid	7.12	ns
t_{RSTAF}	RESET Low to Almost Empty/Full Flag Valid	26.33	ns
t_{RSTBQ}	RESET Low to Data Out Low on RD (flow-through)	4.09	ns
	RESET Low to Data Out Low on RD (pipelined)	4.09	ns
$t_{REMRSTB}$	RESET Removal	1.23	ns
$t_{RECRSTB}$	RESET Recovery	6.58	ns
$t_{MPWRSTB}$	RESET Minimum Pulse Width	1.18	ns
t_{CYC}	Clock Cycle Time	10.90	ns
F_{MAX}	Maximum Frequency for FIFO	92	MHz

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

CS281	
Pin Number	**AGL600 Function**
R15	IO94RSB2
R16	GDA1/IO88PPB1
R18	GDB0/IO87NPB1
R19	GDC0/IO86NPB1
T1	IO148PPB3
T2	GEC0/IO146NPB3
T4	GEB0/IO145NPB3
T5	IO132RSB2
T6	IO136RSB2
T7	IO130RSB2
T8	IO126RSB2
T9	IO120RSB2
T10	GND
T11	IO113RSB2
T12	IO104RSB2
T13	IO101RSB2
T14	IO98RSB2
T15	GDC2/IO91RSB2
T16	TMS
T18	VJTAG
T19	GDB1/IO87PPB1
U1	IO147PDB3
U2	GEA1/IO144PPB3
U6	IO131RSB2
U14	IO99RSB2
U18	TRST
U19	GDA0/IO88NPB1
V1	IO147NDB3
V2	VCCIB3
V3	GEC2/IO141RSB2
V4	IO140RSB2
V5	IO135RSB2
V6	GND
V7	IO125RSB2
V8	IO122RSB2
V9	IO116RSB2

CS281	
Pin Number	**AGL600 Function**
V10	IO112RSB2
V11	IO110RSB2
V12	IO108RSB2
V13	IO102RSB2
V14	GND
V15	IO93RSB2
V16	GDA2/IO89RSB2
V17	TDI
V18	VCCIB2
V19	TDO
W1	GND
W2	FF/GEB2/IO142RSB2
W3	IO139RSB2
W4	IO137RSB2
W5	IO134RSB2
W6	IO133RSB2
W7	IO128RSB2
W8	IO124RSB2
W9	IO119RSB2
W10	VCCIB2
W11	IO109RSB2
W12	IO107RSB2
W13	IO105RSB2
W14	IO100RSB2
W15	IO96RSB2
W16	IO92RSB2
W17	GDB2/IO90RSB2
W18	TCK
W19	GND

QN132	
Pin Number	**AGL030 Function**
C17	IO47RSB1
C18	NC
C19	TCK
C20	NC
C21	VPUMP
C22	VJTAG
C23	NC
C24	NC
C25	NC
C26	GDB0/IO34RSB0
C27	NC
C28	VCCIB0
C29	IO28RSB0
C30	IO25RSB0
C31	IO24RSB0
C32	IO21RSB0
C33	NC
C34	NC
C35	VCCIB0
C36	IO13RSB0
C37	IO10RSB0
C38	IO07RSB0
C39	IO03RSB0
C40	IO00RSB0
D1	GND
D2	GND
D3	GND
D4	GND

FG144	
Pin Number	**AGL600 Function**
K1	GEB0/IO145NDB3
K2	GEA1/IO144PDB3
K3	GEA0/IO144NDB3
K4	GEA2/IO143RSB2
K5	IO119RSB2
K6	IO111RSB2
K7	GND
K8	IO94RSB2
K9	GDC2/IO91RSB2
K10	GND
K11	GDA0/IO88NDB1
K12	GDB0/IO87NDB1
L1	GND
L2	VMV3
L3	FF/GEB2/IO142RSB2
L4	IO136RSB2
L5	VCCIB2
L6	IO115RSB2
L7	IO103RSB2
L8	IO97RSB2
L9	TMS
L10	VJTAG
L11	VMV2
L12	TRST
M1	GNDQ
M2	GEC2/IO141RSB2
M3	IO138RSB2
M4	IO123RSB2
M5	IO126RSB2
M6	IO134RSB2
M7	IO108RSB2
M8	IO99RSB2
M9	TDI
M10	VCCIB2
M11	VPUMP
M12	GNDQ

FG256	
Pin Number	**AGL400 Function**
R5	IO123RSB2
R6	IO118RSB2
R7	IO112RSB2
R8	IO106RSB2
R9	IO100RSB2
R10	IO96RSB2
R11	IO89RSB2
R12	IO85RSB2
R13	GDB2/IO81RSB2
R14	TDI
R15	NC
R16	TDO
T1	GND
T2	IO126RSB2
T3	FF/GEB2/IO133RSB2
T4	IO124RSB2
T5	IO116RSB2
T6	IO113RSB2
T7	IO107RSB2
T8	IO105RSB2
T9	IO102RSB2
T10	IO97RSB2
T11	IO92RSB2
T12	GDC2/IO82RSB2
T13	IO86RSB2
T14	GDA2/IO80RSB2
T15	TMS
T16	GND

FG256	
Pin Number	**AGL600 Function**
H3	GFB1/IO163PPB3
H4	VCOMPLF
H5	GFC0/IO164NPB3
H6	VCC
H7	GND
H8	GND
H9	GND
H10	GND
H11	VCC
H12	GCC0/IO69NPB1
H13	GCB1/IO70PPB1
H14	GCA0/IO71NPB1
H15	IO67NPB1
H16	GCB0/IO70NPB1
J1	GFA2/IO161PPB3
J2	GFA1/IO162PDB3
J3	VCCPLF
J4	IO160NDB3
J5	GFB2/IO160PDB3
J6	VCC
J7	GND
J8	GND
J9	GND
J10	GND
J11	VCC
J12	GCB2/IO73PPB1
J13	GCA1/IO71PPB1
J14	GCC2/IO74PPB1
J15	IO80PPB1
J16	GCA2/IO72PDB1
K1	GFC2/IO159PDB3
K2	IO161NPB3
K3	IO156PPB3
K4	IO129RSB2
K5	VCCIB3
K6	VCC
K7	GND
K8	GND

FG256	
Pin Number	**AGL600 Function**
K9	GND
K10	GND
K11	VCC
K12	VCCIB1
K13	IO73NPB1
K14	IO80NPB1
K15	IO74NPB1
K16	IO72NDB1
L1	IO159NDB3
L2	IO156NPB3
L3	IO151PPB3
L4	IO158PSB3
L5	VCCIB3
L6	GND
L7	VCC
L8	VCC
L9	VCC
L10	VCC
L11	GND
L12	VCCIB1
L13	GDB0/IO87NPB1
L14	IO85NDB1
L15	IO85PDB1
L16	IO84PDB1
M1	IO150PDB3
M2	IO151NPB3
M3	IO147NPB3
M4	GEC0/IO146NPB3
M5	VMV3
M6	VCCIB2
M7	VCCIB2
M8	IO117RSB2
M9	IO110RSB2
M10	VCCIB2
M11	VCCIB2
M12	VMV2
M13	IO94RSB2
M14	GDB1/IO87PPB1

FG256	
Pin Number	**AGL600 Function**
M15	GDC1/IO86PDB1
M16	IO84NDB1
N1	IO150NDB3
N2	IO147PPB3
N3	GEC1/IO146PPB3
N4	IO140RSB2
N5	GNDQ
N6	GEA2/IO143RSB2
N7	IO126RSB2
N8	IO120RSB2
N9	IO108RSB2
N10	IO103RSB2
N11	IO99RSB2
N12	GNDQ
N13	IO92RSB2
N14	VJTAG
N15	GDC0/IO86NDB1
N16	GDA1/IO88PDB1
P1	GEB1/IO145PDB3
P2	GEB0/IO145NDB3
P3	VMV2
P4	IO138RSB2
P5	IO136RSB2
P6	IO131RSB2
P7	IO124RSB2
P8	IO119RSB2
P9	IO107RSB2
P10	IO104RSB2
P11	IO97RSB2
P12	VMV1
P13	TCK
P14	VPUMP
P15	TRST
P16	GDA0/IO88NDB1
R1	GEA1/IO144PDB3
R2	GEA0/IO144NDB3
R3	IO139RSB2
R4	GEC2/IO141RSB2

FG484	
Pin Number	**AGL600 Function**
A1	GND
A2	GND
A3	VCCIB0
A4	NC
A5	NC
A6	IO09RSB0
A7	IO15RSB0
A8	NC
A9	NC
A10	IO22RSB0
A11	IO23RSB0
A12	IO29RSB0
A13	IO35RSB0
A14	NC
A15	NC
A16	IO46RSB0
A17	IO48RSB0
A18	NC
A19	NC
A20	VCCIB0
A21	GND
A22	GND
AA1	GND
AA2	VCCIB3
AA3	NC
AA4	NC
AA5	NC
AA6	IO135RSB2
AA7	IO133RSB2
AA8	NC
AA9	NC
AA10	NC
AA11	NC
AA12	NC
AA13	NC
AA14	NC

FG484	
Pin Number	**AGL600 Function**
AA15	NC
AA16	IO101RSB2
AA17	NC
AA18	NC
AA19	NC
AA20	NC
AA21	VCCIB1
AA22	GND
AB1	GND
AB2	GND
AB3	VCCIB2
AB4	NC
AB5	NC
AB6	IO130RSB2
AB7	IO128RSB2
AB8	IO122RSB2
AB9	IO116RSB2
AB10	NC
AB11	NC
AB12	IO113RSB2
AB13	IO112RSB2
AB14	NC
AB15	NC
AB16	IO100RSB2
AB17	IO95RSB2
AB18	NC
AB19	NC
AB20	VCCIB2
AB21	GND
AB22	GND
B1	GND
B2	VCCIB3
B3	NC
B4	NC
B5	NC
B6	IO08RSB0

FG484	
Pin Number	**AGL600 Function**
B7	IO12RSB0
B8	NC
B9	NC
B10	IO17RSB0
B11	NC
B12	NC
B13	IO36RSB0
B14	NC
B15	NC
B16	IO47RSB0
B17	IO49RSB0
B18	NC
B19	NC
B20	NC
B21	VCCIB1
B22	GND
C1	VCCIB3
C2	NC
C3	NC
C4	NC
C5	GND
C6	NC
C7	NC
C8	VCC
C9	VCC
C10	NC
C11	NC
C12	NC
C13	NC
C14	VCC
C15	VCC
C16	NC
C17	NC
C18	GND
C19	NC
C20	NC

FG484	
Pin Number	**AGL600 Function**
Y7	NC
Y8	VCC
Y9	VCC
Y10	NC
Y11	NC
Y12	NC
Y13	NC
Y14	VCC
Y15	VCC
Y16	NC
Y17	NC
Y18	GND
Y19	NC
Y20	NC
Y21	NC
Y22	VCCIB1

FG484	
Pin Number	**AGL1000 Function**
A1	GND
A2	GND
A3	VCCIB0
A4	IO07RSB0
A5	IO09RSB0
A6	IO13RSB0
A7	IO18RSB0
A8	IO20RSB0
A9	IO26RSB0
A10	IO32RSB0
A11	IO40RSB0
A12	IO41RSB0
A13	IO53RSB0
A14	IO59RSB0
A15	IO64RSB0
A16	IO65RSB0
A17	IO67RSB0
A18	IO69RSB0
A19	NC
A20	VCCIB0
A21	GND
A22	GND
AA1	GND
AA2	VCCIB3
AA3	NC
AA4	IO181RSB2
AA5	IO178RSB2
AA6	IO175RSB2
AA7	IO169RSB2
AA8	IO166RSB2
AA9	IO160RSB2
AA10	IO152RSB2
AA11	IO146RSB2
AA12	IO139RSB2
AA13	IO133RSB2
AA14	NC

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